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**ABSTRACT**

Various technologies described herein pertain to a heat spreader for an autonomous vehicle computing device. The heat spreader includes a top surface, a bottom surface, and a side surface. The top surface of the heat spreader is thermally conductive. The top surface of the heat spreader includes a section that is sized and shaped to align with a heat generating component (e.g., on a printed circuit board assembly). The top surface of the heat spreader is configured to receive heat from the heat generating component. The bottom surface of the heat spreader includes externally integrated fins. The heat spreader is configured to dissipate the heat from the heat generating component such that the heat from the heat generating component flows from the top surface to the externally integrated fins on the bottom surface.

